

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

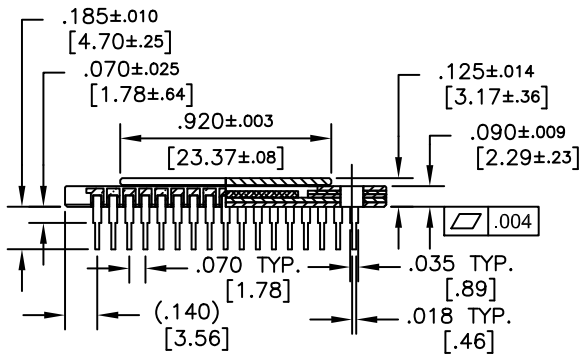
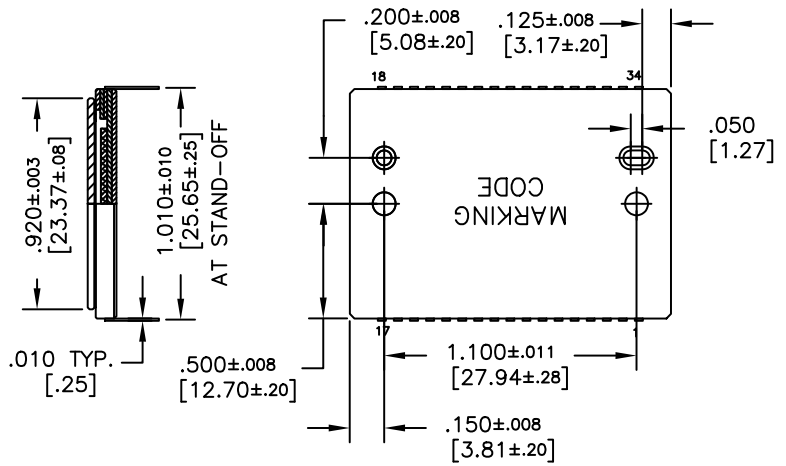
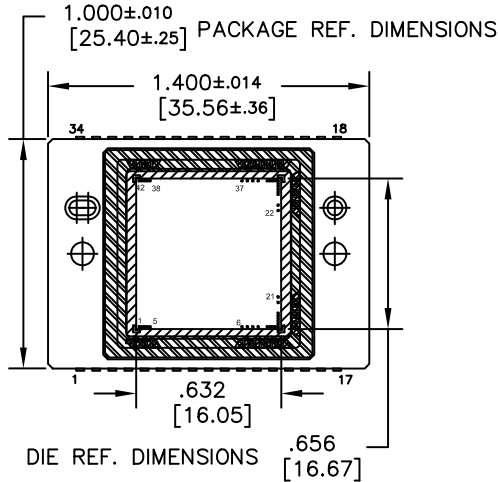
ON Semiconductor®



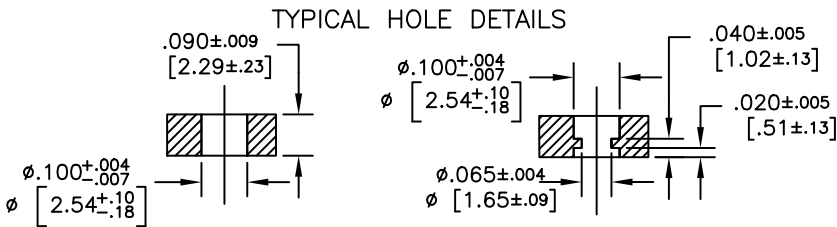
CERAMIC DIP 34, 35.56x20.83

CASE 125BJ
ISSUE O

DATE 03 JUL 2014



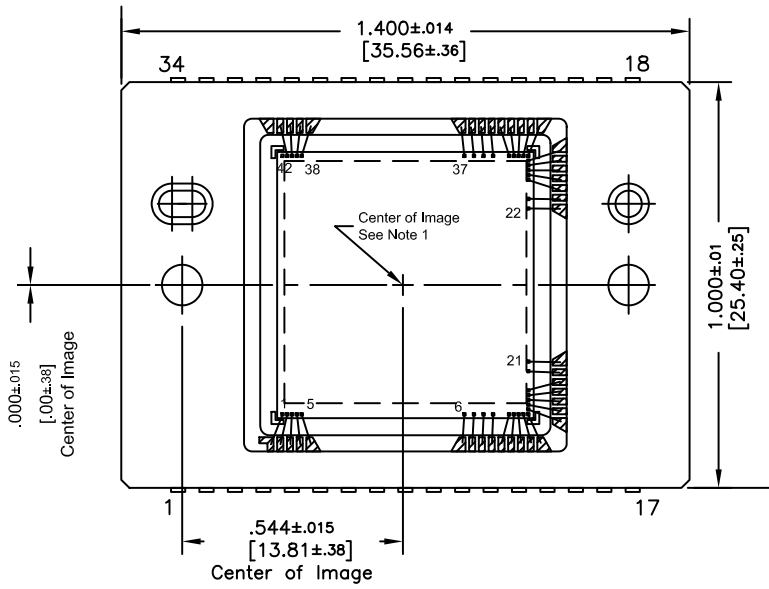
NOTES:
 1. COVER GLASS IS MANUALLY PLACED AND ALIGNED WITH THE AID OF A MECHANICAL FIXTURE.



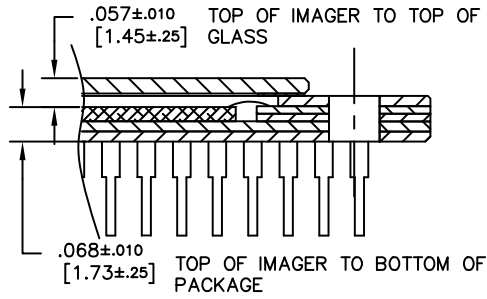
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- NOTES:
1. CENTER OF IMAGE IS OFFSET FROM CENTER OF PACKAGE BY COORDINATES (-.157, 0.000)mm NOMINAL.
 2. DIE IS ALIGNED WITHIN +/- 1 DEGREES OF ANY PACKAGE CAVITY EDGE.



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